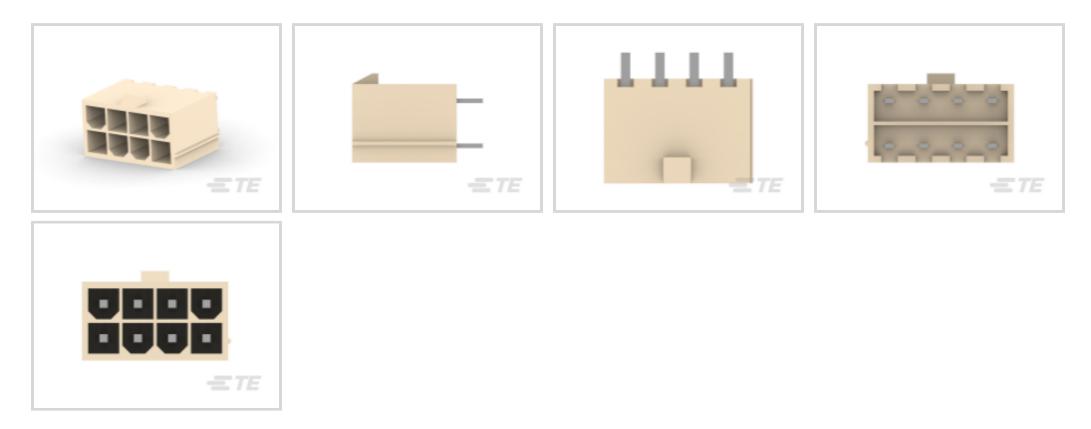


## **ATX Power**

TE Internal #: 4-1775099-2 PCB Mount Header, Vertical, Wire-to-Board, 8 Position, 1.4 mm [. 055 in] Centerline, Tin, Through Hole - Solder, Power, Ivory, Tray, ATX Power

#### View on TE.com >

Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Header

Connector System: Wire-to-Board

Number of Positions: 8

Number of Rows: 2

Centerline (Pitch): 1.4 mm [.055 in]

## Features

**E** 

## Product Type Features

PCB Connector Assembly Type	PCB Mount Header
Connector System	Wire-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Number of Positions	8
Number of Rows	2
PCB Mount Orientation	Vertical
Electrical Characteristics	
Operating Voltage	250 VAC
Body Features	
Primary Product Color	lvory
Contact Features	

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PCB Mount Header, Vertical, Wire-to-Board, 8 Position, 1.4 mm [.055 in] Centerline, Tin, Through Hole - Solder, Power, Ivory, Tray, ATX Power



PCB Contact Termination Area Plating Material Thickness	3.05 μm[120.07 μin]
Contact Layout	Matrix
Mating Tab Width	1.14 mm[.044 in]
Mating Tab Thickness	1.1 mm[.043 in]
Contact Underplating Material Thickness	1.27 μm[50 μin]
Contact Mating Area Plating Material Thickness	3.05 μm[120.07 μin]
PCB Contact Termination Area Plating Material Finish	Matte
Contact Mating Area Plating Material Finish	Matte
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin
Contact Mating Area Plating Material	Tin
Contact Type	Pin
Contact Current Rating (Max)	9 A
Termination Features	

Rectangular Termination Post & Tail Thickness	.55 mm[.021 in]
Rectangular Termination Post & Tail Width	1.14 mm[.044 in]
Termination Method to PCB	Through Hole - Solder

### **Mechanical Attachment**

	10/28/2024 08:2
Operation/Application	
Operating Temperature Range	-25 – 85 °C[-13 – 185 °F]
Usage Conditions	
Row-to-Row Spacing	4.2 mm[.165 in]
Dimensions	
Centerline (Pitch)	1.4 mm[.055 in]
Housing Material	PA 9T
Housing Features	
PCB Mount Retention	With
PCB Mount Alignment	Without
Mating Alignment	With
Connector Mounting Type	Board Mount
Mating Retention	Without
Mating Alignment Type	Polarization

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PCB Mount Header, Vertical, Wire-to-Board, 8 Position, 1.4 mm [.055 in] Centerline, Tin, Through Hole - Solder, Power, Ivory, Tray, ATX Power



Circuit Application	Power
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Method	Tray
Product Compliance For compliance documentation, visit the product page on TE.com>	
EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Out of Scope
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JAN 2023 (233) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 265°C

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

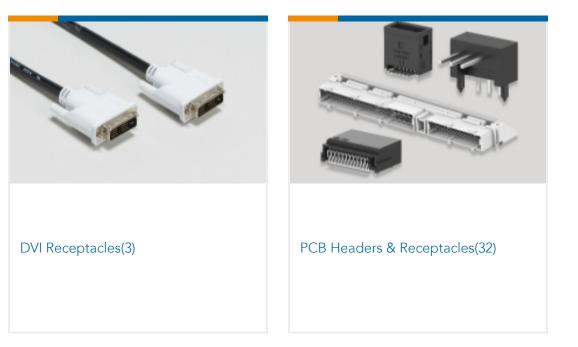
## **Compatible Parts**

PCB Mount Header, Vertical, Wire-to-Board, 8 Position, 1.4 mm [.055 in] Centerline, Tin, Through Hole - Solder, Power, Ivory, Tray, ATX Power



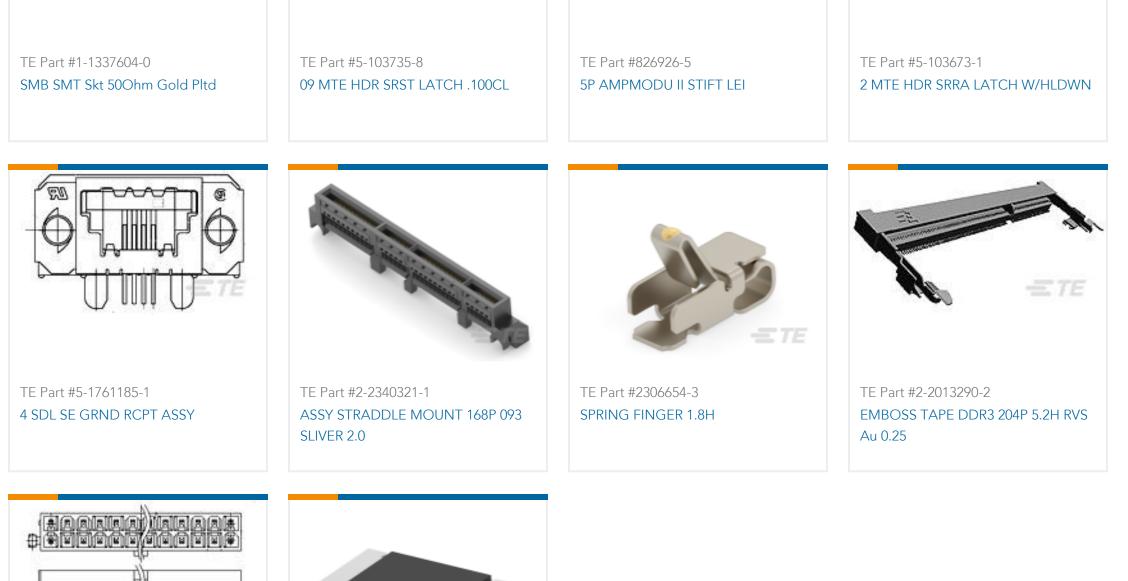
TE Part # 3-1775099-2 ATX PWR CONN 1 BDLK 8 POS

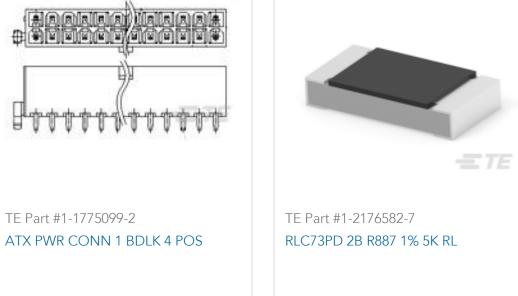
# Also in the Series | ATX Power



# Customers Also Bought







PCB Mount Header, Vertical, Wire-to-Board, 8 Position, 1.4 mm [.055 in] Centerline, Tin, Through Hole - Solder, Power, Ivory, Tray, ATX Power



## Documents

CAD Files 3D PDF

3D

**Customer View Model** 

ENG\_CVM\_CVM\_4-1775099-2\_E.2d\_dxf.zip

English

Customer View Model

ENG\_CVM\_CVM\_4-1775099-2\_E.3d\_igs.zip

English

Customer View Model ENG\_CVM\_CVM\_4-1775099-2\_E.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

**Product Specifications** 

**Product Specification** 

English

**Product Specification** 

Japanese

AMP Mini CT Connector 1.5mm Pitch (Crimp Type), Lead Free Version

Japanese